

FEATURES

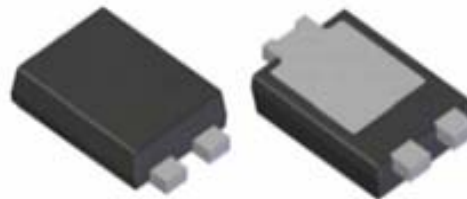
- High current capability, low forward voltage
- Excellent high temperature stability
- Low power loss, and high efficiency
- High Forward Surge Capability
- Patented package technology

APPLICATIONS

- Switching mode power supply applications
- Portable equipment battery applications
- High frequency rectification
- DC/DC Converter
- Designed as bypass diodes for solar panels

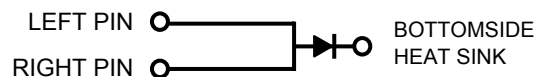
SYMBOL

Package: TO-277B (SMD)



Top View

Bottom View



特征：超薄封装，体积小，超低压降等特点

典型应用：手机充电器、平板电脑、移动电源、其他充电器、1A、2A端口充电电路

以及太阳能电池、汽车电子、电脑周边、家电等产品，适合高密度PCB、高效率适配器电源

H1045L可代替同类器件型号：

SR1045L、MBR1045、MBR1045CT、MCC1045UL、SB1045L、SV1045、UL1045、SBR10U45SP5、MBR1045ULPS

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$, unless otherwise specified)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive peak reverse voltage	V_{RRM}	45	V
Maximum DC blocking voltage	V_{RM}	45	
Average forward current	$I_{F(AV)}$	10	A
Surge non repetitive forward current (8.3ms single half sine- wave)	I_{FSM}	278	
Single pulse davalanche energy ($I_{AS}=12\text{A}$, $L=10\text{mH}$)	E_{AS}	530	mJ
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-55~+150	

■ Thermal Characteristics

CHARACTERISTIC	SYMBOL	RATING	UNIT
Thermal Resistance, Junction-to-Ambiene	R_{QJA}	31	$^{\circ}\text{C}/\text{W}$

■ Electrical Characteristics

Characterisrtic	Symbol	Test Condition	Rating			UNIT
			Min	Typ	Max	
Fo rward voltage drop	V_F	$I_F=2\text{A}$	--	0.31	0.35	V
		$I_F=8\text{A}$	--	0.37	0.38	
		$I_F=10\text{A}$	$T_J=25^{\circ}\text{C}$	--	0.41	
			$T_J=100^{\circ}\text{C}$	--	0.36	
Reverse leakage current	I_R	$V_R=\text{Max. } V_{RRM}$	$T_J=25^{\circ}\text{C}$	--	0.06	mA
			$T_J=125^{\circ}\text{C}$	--	17	

■ Rating and Characteristic Curves

Fig-1. Typical Forward Characteristics

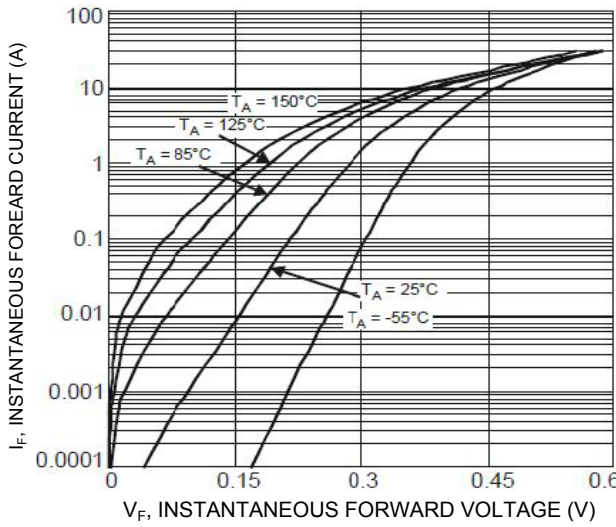


Fig-2. Typical Reverse Characteristics

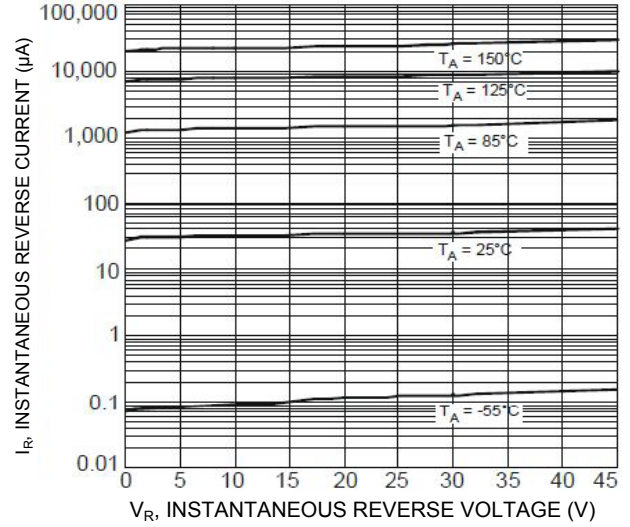


Fig-3. Forward Current Derating Curve

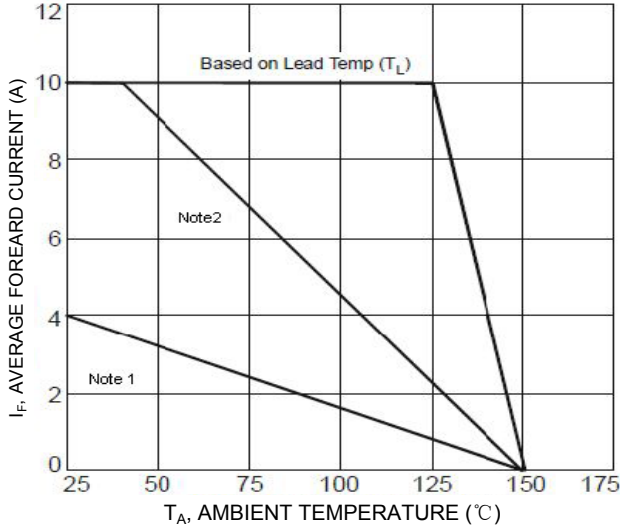


Fig-4. Operating Temperature Derating Curve

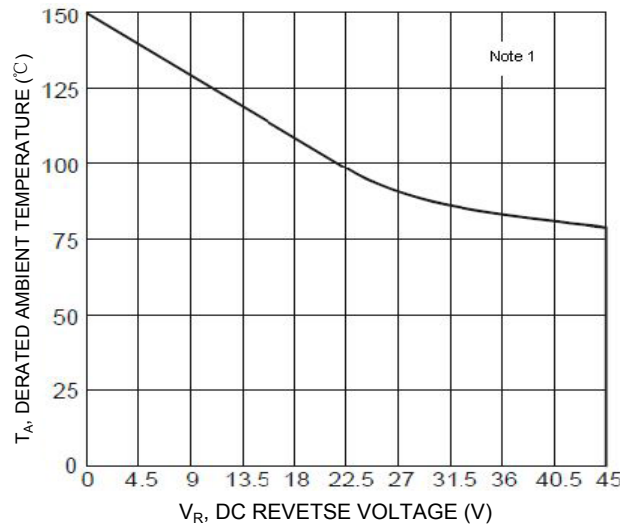
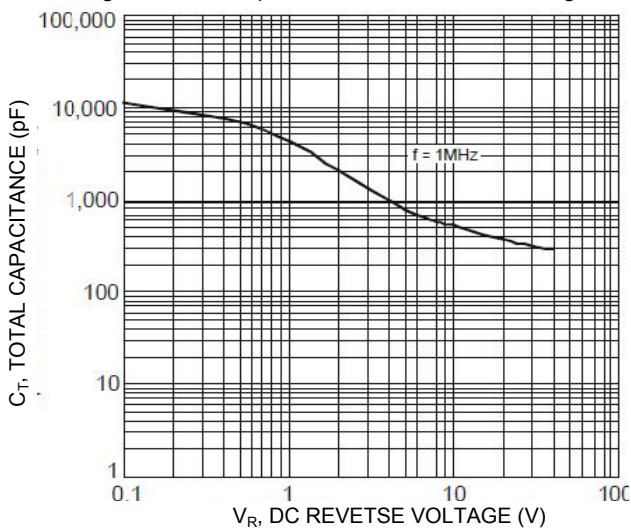
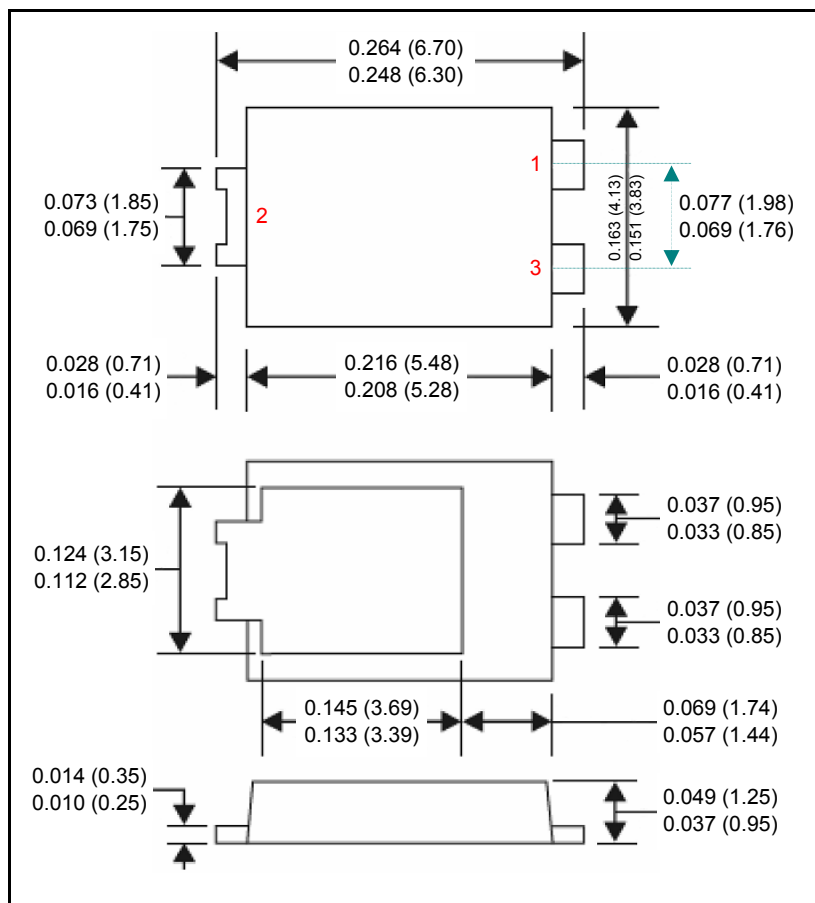


Fig-5. Total Capacitance VS. Reverse Voltage

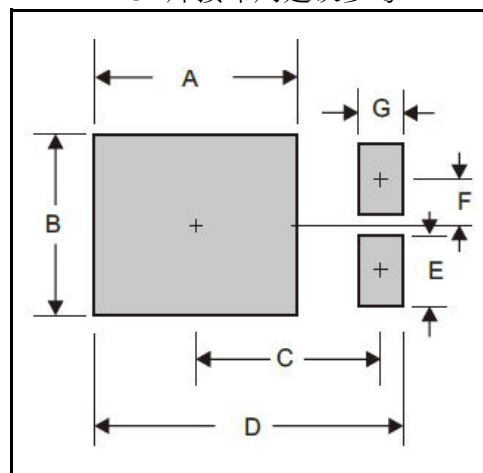


TO-277B Package Dimensions inch (millimeters) TO-277B SMD 表面贴封装尺寸数据: 英寸(毫米)

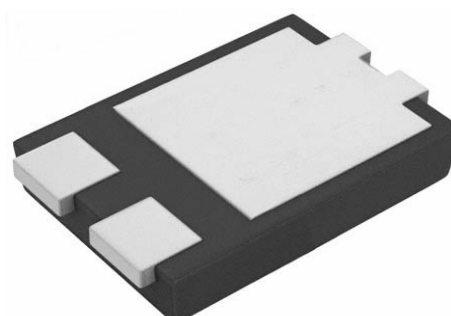


SMD表面贴装
TO-277
TO-277B
QFN5×6
POWERDI5

Suggested Pad Layout
PCB焊接布局建议参考



A	B	C	D	E	F	G
0.185(4.70)	0.142(3.60)	0.152(3.87)	0.260(6.60)	0.055(1.40)	0.035(0.90)	0.031(0.80)



TO-277B（表面贴封装）包装方式
载带卷盘包装: Tape & Reel
每卷数量: 5000只 (5Kpcs/Reel)
每盒数量: 10000只 (10Kpcs/BOX)



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